

2224-0163P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant:

Tatsuya NAKANO

Appl. No.:

09/463,059

Filed:

January 19, 2000

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Examiner: Unassignom.

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For:

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L E T T E R

Assistant Commissioner for Patents Washington, DC 20231

February 6, 2001

Sir:

Under the provisions of MPEP § 2001.06(b), the Examiner is hereby advised of the following co-pending U.S. Application(s):

Appl. No.	Filing Date	Group
09/600,717	July 20, 2000	1100

The subject matter contained in the above-listed co-pending U.S. application(s) may be deemed to relate to the present application, and thus may be material to the prosecution of this instant application.

Copies of cited U.S. patent application(s) (specification, claims, and the drawings) or copies of the portion of the application which caused it to be cited, including any claims directed to that portion are attached hereto.

Appl. No. 09/463,059

The materials in the envelope are considered trade secrets and are being submitted for consideration under M.P.E.P.

The above-listed co-pending application(s) is(are) not to be construed as prior art. By bringing the above-listed application(s) to the attention of the Examiner, Applicant(s) do(does) NOT waive any confidentiality concerning the above-listed co-pending application(s) or this application. See MPEP § 101. Furthermore, if said application(s) should not mature into patents, such application(s) should be preserved in secrecy under the provisions of 35 U.S.C. § 122 and 37 C.F.R. § 1.14.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fee required under 37 C.F.R. §§ 1.16 or 1.17; particularly, extension of time fees.

Respectfully submitted,

BIRCH, STEWART, KOLASCH & BIRCH, LLP

By <u>Elward H. Valence #19896</u> For Raymond C. Stewart, #21,066

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